



Product Change Notification: CAAN-25TWTH492

Date:

16-Jun-2026

Product Category:

Memory

Notification Subject:

CCB 8031 Final Notice: Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families.

Affected CPNs:

[CAAN-25TWTH492_Affected_CPN_06162026.pdf](#)

[CAAN-25TWTH492_Affected_CPN_06162026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families.

Pre and Post Summary Changes:

	Pre Change			Post Change	Change (Yes/No)
Fabrication Location	Microchip Technology	Microchip Technology	Microchip Technology	Microchip Technology	Yes

	Tempe – Fab 2 (TMGR)	Gresham – Fab 4 (GRTM)	Colorado (MCSO)	Colorado (MCSO)	
Wafer Technology	150k		35.5k	36.3k	Yes
Wafer Size	8"	8"	6"	6"	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on-time delivery performance by qualifying a new fabrication location (MCSO - FAB 5).

Change Implementation Status: In Progress

Estimated First Ship Date: 10 July 2026 (date code: 2628)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	January 2026					>	June 2026				July 2026				
Work Week	01	02	03	04	05		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date					X										
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date												X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: January 30, 2026: Issued initial notification.

June 16, 2026: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on July 10, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-25TWTH492_Qual_Report.pdf](#)

Please contact your local **[Microchip sales office](#)** with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the **[PCN home page](#)** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

93AA86BT-I/OT
93AA86BT-I/SN
93AA86BT-I/ST
93AA86C-I/MS
93AA86C-I/P
93AA86C-I/SN
93LC76B-I/ST
93LC76BT-E/MS
93LC76BT-E/OT
93LC76BT-E/SN
93LC76BT-E/ST
93LC76BT-I/MS
93LC76BT-I/OT
93LC76BT-I/SN
93LC76BT-I/ST
93LC76C-E/MS
93C76A-I/SN
93C76A-I/ST
93C76AT-E/MS
93C76AT-E/OT
93C76AT-E/SN
93C76AT-E/ST
93C76AT-I/MS
93C76AT-I/OT
93C76AT-I/SN
93C76AT-I/ST
93C76B-E/MS
93C76B-E/P
93C76B-E/SN
93C76B-E/ST
93C76B-I/MS
93C76B-I/P

93C76B-I/SN

93C76B-I/ST

93C76BT-E/MS

93C76BT-E/OT

93C76BT-E/SN

93C76BT-E/ST

93C76BT-I/MS

93C76BT-I/OT

93C76BT-I/SN

93C76BT-I/ST

93C76C-E/MS

93C76C-E/P

93C76C-E/SN

93C76C-E/ST

93C76C-I/MS

93C76C-I/P

93C76C-I/SN

93C76C-I/ST

93C76CT-E/MNY

93C76CT-E/MS

93C76CT-E/SN

93C76CT-E/ST

93C76CT-I/MC

93C76CT-I/MNY

93C76CT-I/MS

93C76CT-I/SN

93C76CT-I/ST

93C86A-E/MS

93C86A-E/P

93C86A-E/SN

93C86A-E/ST

93C86A-I/MS

93C86A-I/P

93C86A-I/SN

93C86A-I/ST

93C86AT-E/MS

93C86AT-E/OT

93C86AT-E/SN

93C86AT-E/ST

93C86AT-I/MS

93C86AT-I/OT

93C86AT-I/SN

93C86AT-I/ST

93C86B-E/MS

93C86B-E/P

93C86B-E/SN

93C86B-E/ST

93C86B-I/MS

93C86B-I/P

93C86B-I/SN

93C86B-I/ST

93C86BT-E/MS

93C86BT-E/OT

93C86BT-E/SN

93C86BT-E/ST

93C86BT-I/MS

93C86BT-I/OT

93C86BT-I/SN

93C86BT-I/ST

93C86C-E/MS

93C86C-E/P

93C86C-E/SN

93C86C-E/ST

93C86C-I/MS

93C86C-I/P

93C86C-I/SN

93C86C-I/ST

93C86CT-E/MNY

93C86CT-E/MS

93C86CT-E/SN

93C86CT-E/ST

CAAN-25TWITH492 - CCB 8031 Final Notice: Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families.

93C86CT-I/MC

93C86CT-I/MNY

93C86CT-I/MS

93C86CT-I/SN

93C86CT-I/ST

93LC76A-E/MS

93LC76A-E/P

93LC76A-E/SN

93LC76A-E/ST

93LC76A-I/MS

93LC76A-I/P

93LC76A-I/SN

93LC76A-I/ST

93LC76AT-E/MS

93LC76AT-E/OT

93LC76AT-E/SN

93LC76AT-E/ST

93LC76AT-I/MS

93LC76AT-I/OT

93LC76AT-I/SN

93LC76AT-I/ST

93LC76B-E/MS

93LC76B-E/P

93LC76B-E/SN

93LC76B-E/ST

93LC76B-I/MS

93LC76B-I/P

93LC76B-I/SN

93AA76A-I/MS

93AA76A-I/P

93AA76A-I/SN

93AA76A-I/ST

93AA76AT-I/MS

93AA76AT-I/OT

93AA76AT-I/SN

93AA76AT-I/ST

93AA76B-I/MS

93AA76B-I/P

93AA76B-I/SN

93AA76B-I/ST

93AA76BT-I/MS

93AA76BT-I/OT

93AA76BT-I/SN

93AA76BT-I/ST

93AA76C-I/MS

93AA76C-I/P

93LC76C-E/P

93LC76C-E/SN

93LC76C-E/ST

93LC76C-I/MS

93LC76C-I/P

93LC76C-I/SN

93LC76C-I/ST

93LC76CT-E/MNY

93LC76CT-E/MS

93LC76CT-E/SN

93LC76CT-E/ST

93LC76CT-I/MC

93LC76CT-I/MNY

93LC76CT-I/MS

93LC76CT-I/SN

93LC76CT-I/ST

93LC86A-E/MS

93LC86A-E/P

93LC86A-E/SN

93LC86A-E/ST

93LC86A-I/MS

93LC86A-I/P

93LC86A-I/SN

93LC86A-I/ST

93LC86AT-E/MS

93LC86AT-E/OT

93LC86AT-E/SN

93LC86AT-E/ST

93LC86AT-I/MS

93LC86AT-I/OT

93LC86AT-I/SN

93LC86AT-I/ST

93LC86B-E/MS

93LC86B-E/P

93LC86B-E/SN

93LC86B-E/ST

93LC86B-I/MS

93LC86B-I/P

93LC86B-I/SN

93LC86B-I/ST

93LC86BT-E/MS

93LC86BT-E/OT

93LC86BT-E/SN

93LC86BT-E/ST

93LC86BT-I/MS

93LC86BT-I/OT

93LC86BT-I/SN

93LC86BT-I/ST

93LC86C-E/MS

93LC86C-E/P

93LC86C-E/SN

93LC86C-E/ST

93LC86C-I/MS

93LC86C-I/P

93LC86C-I/SN

93LC86C-I/ST

93LC86CT-E/MNY

93LC86CT-E/MS

93LC86CT-E/SN

93LC86CT-E/ST

93LC86CT-I/MC

93LC86CT-I/MNY

93LC86CT-I/MS

93LC86CT-I/SN

93LC86CT-I/ST

AT93C86A-10PU-1.8

AT93C86A-10PU-2.7

AT93C86A-10SU-1.8

AT93C86A-10SU-1.8-T

AT93C86A-10SU-2.7

AT93C86A-10SU-2.7-T

AT93C86A-10TU-1.8

AT93C86A-10TU-1.8-T

AT93C86A-10TU-2.7

AT93C86A-10TU-2.7-T

AT93C86AY6-10YH-1.8-T

AT93C86AY6-10YH-18-E

93AA86C-I/ST

93AA86CT-I/MC

93AA86CT-I/MNY

93AA86CT-I/MS

93AA86CT-I/SN

93AA86CT-I/ST

93C76A-E/MS

93C76A-E/P

93C76A-E/SN

93C76A-E/ST

93C76A-I/MS

93C76A-I/P

93AA76C-I/SN

93AA76C-I/ST

93AA76CT-I/MC

93AA76CT-I/MNY

93AA76CT-I/MS

93AA76CT-I/SN

93AA76CT-I/ST

CAAN-25TWITH492 - CCB 8031 Final Notice: Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families.

93AA86A-I/MS

93AA86A-I/P

93AA86A-I/SN

93AA86A-I/ST

93AA86AT-I/MS

93AA86AT-I/OT

93AA86AT-I/SN

93AA86AT-I/ST

93AA86B-I/MS

93AA86B-I/P

93AA86B-I/SN

93AA86B-I/ST

93AA86BT-I/MS



MICROCHIP

QUALIFICATION REPORT SUMMARY

PCN #: CAAN-25TWTH492

Date:

June 12, 2026

Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families.

PROCESS QUALIFICATION REPORT

Purpose: Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families.

CCB No.: 8031

Test	Number of Lots	Sample Size (per lot)	Acceptance Criteria	Result
ELFR	1	800	0 fails	Passed
DLT (for EDR/DLT)	1	77	0 fails	Passed
RET (for EDR/RET)	1	231	0 fails	Passed
ESD (HBM)	1	-	0 fails	Passed
ESD (CDM)	1	-	0 fails	Passed
Latch Up	1	12	0 fails	Passed



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of 36.3K process technology for selected products of the 93LC76A, 93AA76A, 93LC76B, 93AA76B, 93C76A, 93C76B, 93C86A, 93C86B, 93LC86A, 93AA86A, 93LC86B, 93AA86B, 93LC76C, 93AA76C, 93C76C, 93C86C, 93LC86C, 93AA86C and AT93C86A device families. This is a qualification by similarity (QBS).
CN	ES220208
QUAL ID	Q18136 Rev. A
MP CODE	365S6QC2XA00
Part No.	25LC640AT-H/SN
Bonding No.	BDE-004738 REV. 03
CCB No.	3379 and 8031
<u>Package</u>	
Type	8L SOIC
Package size	150 mils
<u>Lead Frame</u>	
Paddle size Material	90 x 90 mils
Surface	CDA194
Process	Bare Cu on paddle
Lead Lock	Stamped
Part Number	Yes
Treatment	10100841
<u>Material</u>	Roughened
Epoxy	
Wire	8390A
Mold Compound	Au wire
Plating	G600V
Composition	Matte Tin



MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI191002659.000	MCS0518466473.300	1823J79
MTAI191003913.000	MCS0518466473.300	1823Q4H
MTAI191003922.000	MCS0518466473.300	1823Q7C

Result

☒ Pass ☐ Fail ☐ _____

8L SOIC (.150") assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135	0/135	Pass	

<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 1)	Electrical Test :+25°C,85°C,125°C and 150°C System: NEXTEST_PT	JESD22- A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C,85°C,125°C and 150°C System: NEXTEST_PT			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C,125°C and 150°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
	Stress Condition: -65°C to +150°C, 2000 Cycles System : TABAI ESPEC TSA-70H			231		
	Electrical Test: +85°C,125°C and 150°C System: NEXTEST_PT		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)		15 (0) 15 (0)	0/15 0/15	Pass Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 25°C,85°C,125°C and 150°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs System: SHEL LAB	JESD22- A103		45		45 units
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: NEXTEST_PT		45(0)	0/45	Pass	
	Stress Condition: Bake 175°C, 1000 hrs System: SHEL LAB			45		45 units
	Electrical Test :+ 25°C, 85°C, 125°C and 150°C System: NEXTEST_PT		45(0)	0/45	Pass	
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	